

MJ N-Channel Enhancement Mode Power MOSFET

Description

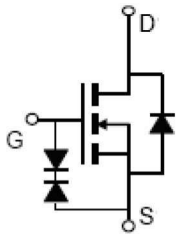
The MJ3011E uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.It is ESD protested.

General Features

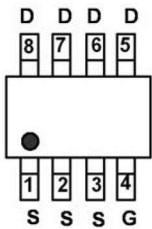
- ◆ $V_{DS}=30V, I_D=11A$
 $R_{DS(ON)} < 10m\Omega @ V_{GS}=10V$
 $R_{DS(ON)} < 14m\Omega @ V_{GS}=4.5V$
ESD Rating: 2000V HBM
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface Mount Package

Application

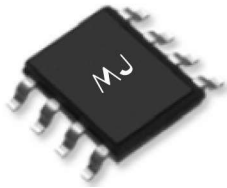
- ◆ PWM application
- ◆ Load switch



Schematic diagram



Marking and pin assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3011E	MJ3011E	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±10	V
Drain Current-Continuous	I_D	11	A
Drain Current-Pulsed ^(Note 1)	I_{DM}	50	A
Maximum Power Dissipation	P_D	2.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	50	℃/W
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Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =250μA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =±10V,V _{DS} =0V	-	-	±10	μA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	1.0	1.5	2.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =8A	-	7	10	mΩ
		V _{GS} =4.5V, I _D =6A	-	10	14	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V,I _D =11A	25	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C _{iss}	V _{DS} =15V,V _{GS} =0V F=1.0MHz	-	1155	-	PF
Output Capacitance	C _{OSS}		-	260	-	PF
Reverse Transfer Capacitance	C _{rss}		-	95	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =15V,R _L =2.2Ω V _{GS} =5V,R _{GEN} =3Ω	-	10	-	nS
Turn-on Rise Time	t _r		-	16	-	nS
Turn-Off Delay Time	t _{d(off)}		-	40	-	nS
Turn-Off Fall Time	t _f		-	10.8	-	nS
Total Gate Charge	Q _g	V _{DS} =15V,I _D =8A V _{GS} =4.5V	-	17.5	-	nC
Gate-Source Charge	Q _{gs}		-	4.5	-	nC
Gate-Drain Charge	Q _{gd}		-	2.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V,I _S =1A	-	-	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	11	A

Notes:

- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t ≤ 10 sec.
- ③ Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

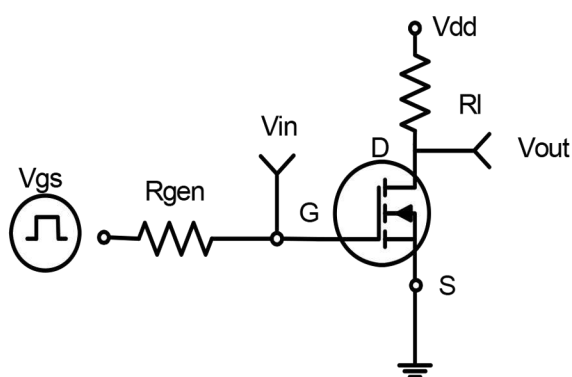


Figure 1 Switching Test Circuit

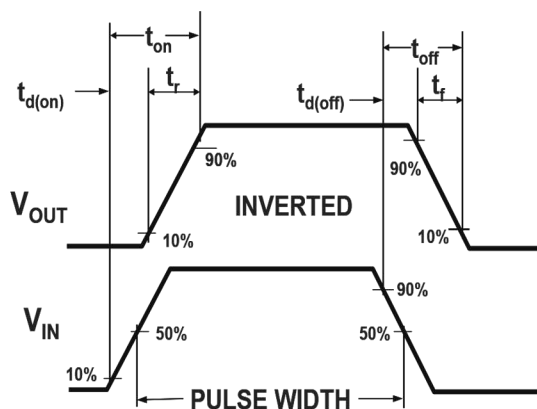
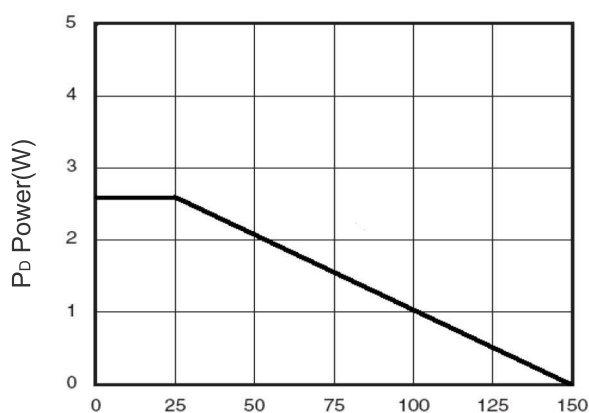
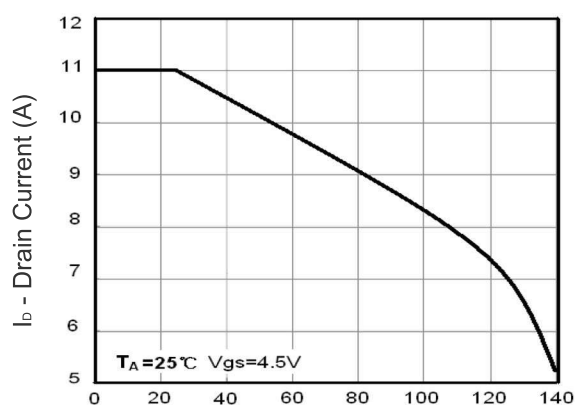


Figure 2 Switching Waveforms



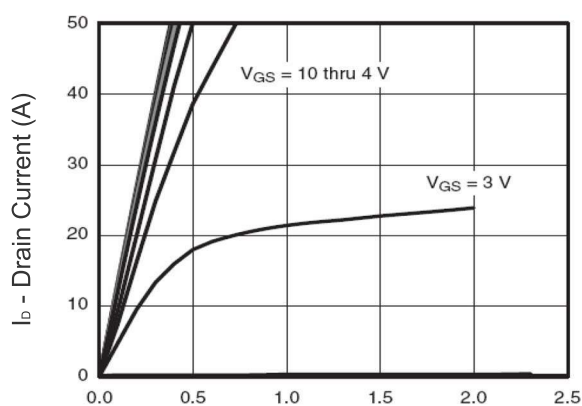
T_J-Junction Temperature(°C)

Figure 3 Power Dissipation



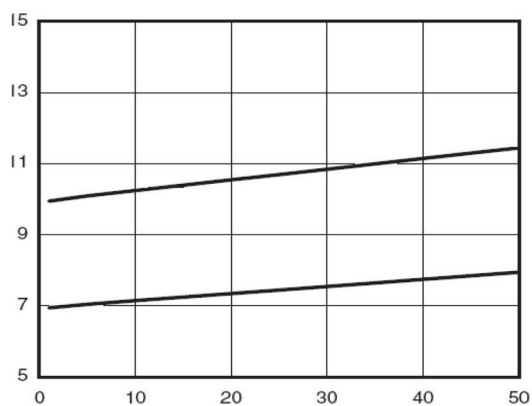
T_J-Junction Temperature(°C)

Figure 4 Drain Current



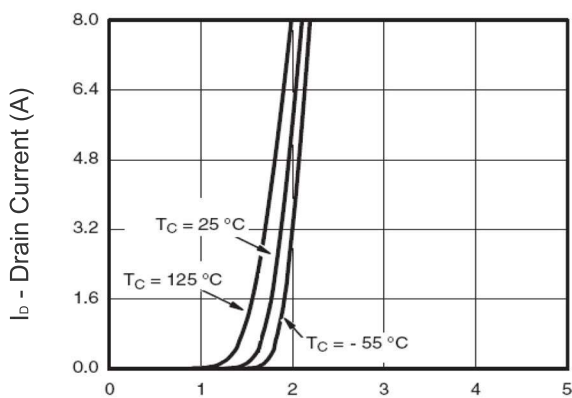
V_{DS} Drain-Source Voltage (V)

Figure 5 Output Characteristics

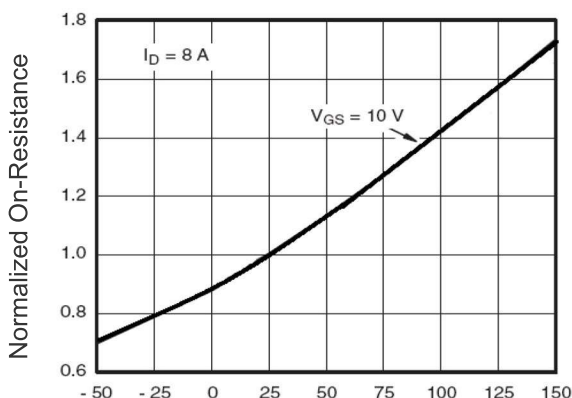


I_D- Drain Current (A)

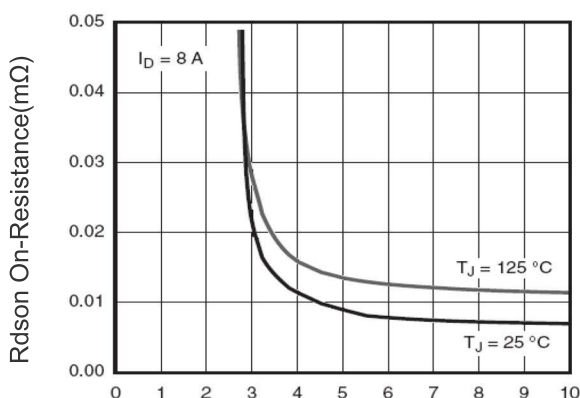
Figure 6 Drain-Source On-Resistance



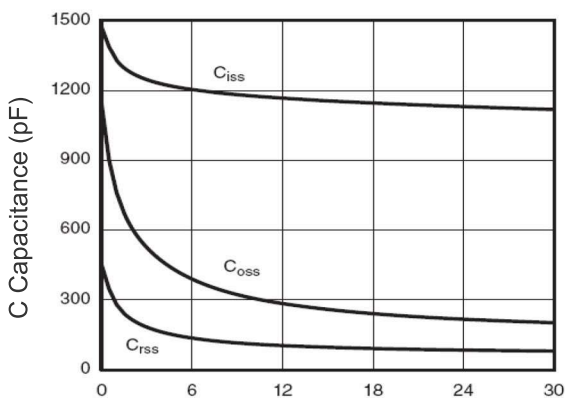
Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



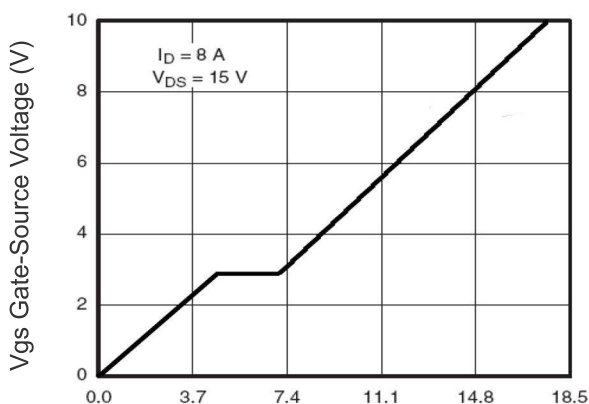
Tj-Junction Temperature(°C)
Figure 8 Drain-Source On-Resistance



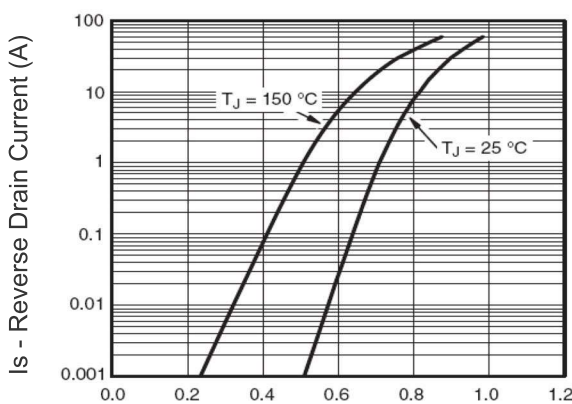
Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs



Vds Drain-Source Voltage (V)
Figure 10 Capacitance vs Vds



Qg Gate Charge (nC)
Figure 11 Gate Charge



Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward

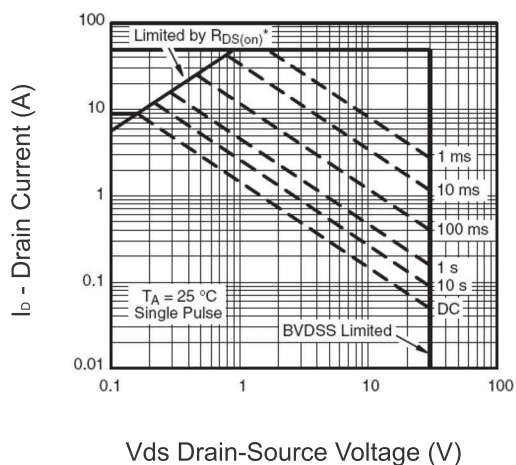


Figure 13 Safe Operation Area

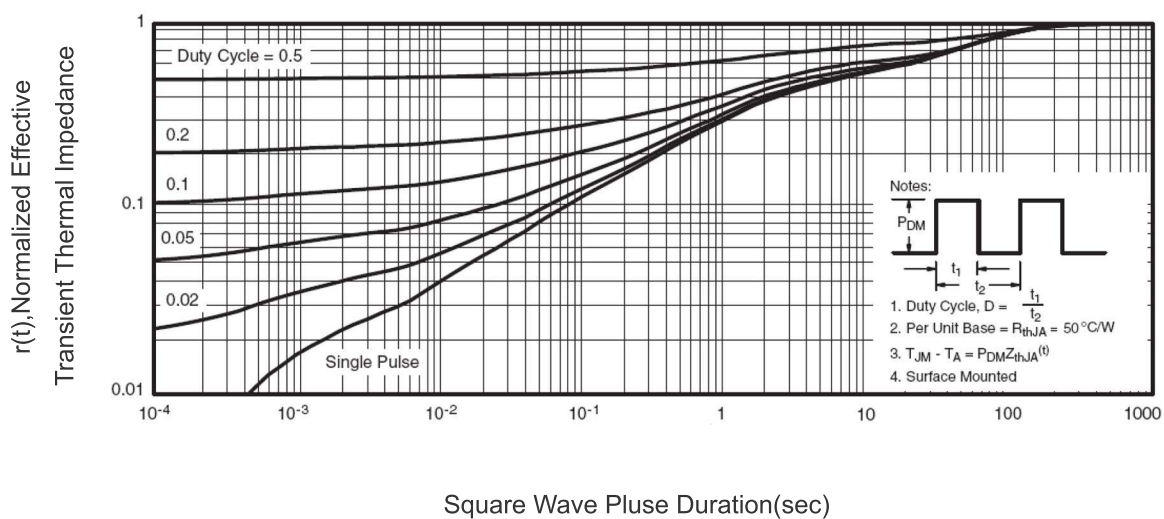
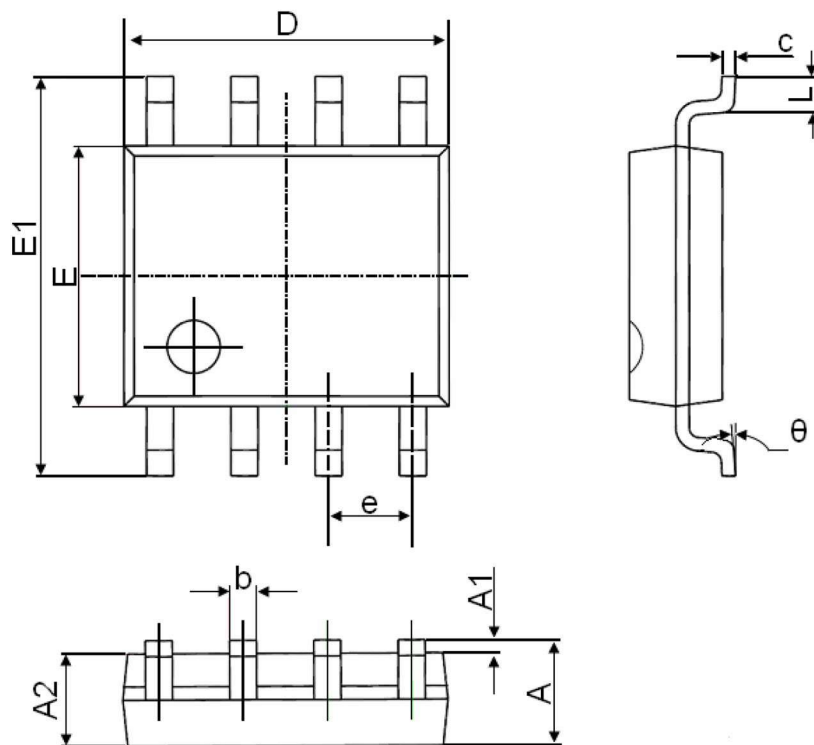


Figure 14 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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